Finance of Spacetimes

BTL / BL

JTAz JDz JDAz



MEK BTL/BL Dual side In-line AOI systems

	Dual side or bottom up only inline full featured inspection	Featuring industry leading GTAz head and optional high clearance JDAz head
	High Speed 60Fps main camera and USB 3 Vision Cameras side cameras	The latest generation of high speed, high quality cameras No capture card requirements.
	Synchronized top and bottom inspection	Top and bottom heads are linked to allow parallel inspection cycles
	Multi-color 3 angle lighting with Line Source Coaxial Lighting and Meniscus Profiler	Reliable solder joint meniscus and pad surface analysis (to find meniscus and paste printing defects)
$\sqrt{}$	Inspects:	use inspection in all stages of the production process
	Flexible classification and reporting scenarios	Integrate AOI efficiently in your existing operations and factory lay-out
V	Line Sourced DOAL(Direct On Axis Lighting) coaxial lighting system with high resolution Telecentric Optics	Inspect solder joints without shadow effects from tall components nearby and accurate inspection model building
	Low Noise Large CCD High Speed 24 bit Color Camera	Find defects easier including printing defects on Gold or Cu plated PCB's
	Synthetic Imaging and Spectral Analysis	Powerful algorithms to achieve an optimal balance between defect detection and false reject levels in shortest time
	Triple use of side camera's	Use for automatic inspection, classification and repair
√	Prototype mode for 1st off inspection	Program in minutes to verify your production line is set-up correctly before starting full production
	In height adjustable optical head	Compensate for PCB warp and adapt to tall component and sandwich assemblies





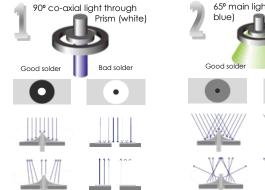
Hardware and Software Features

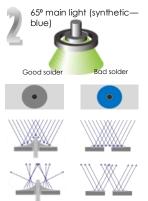
Sixteen possible head combinations

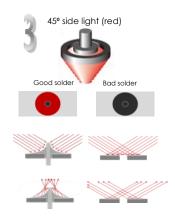
18 Cameras, 9 Top and 9 Bottom Cameras to 2 Camera Single top and Bottom Cameras. The D22X BTL is the ultimate in platform flexibility

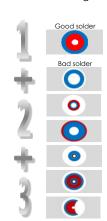
THT Solder Inspection

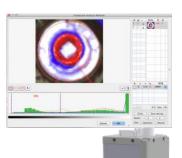
Scalable inspection points for the wide variety of Solder land shapes and pin sizes, Bridge and solder ball detection algorithms.





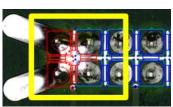






Histogram Analysis algorithms

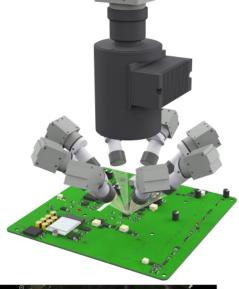
Condition based decision. Tolerances can be set tightly Close to zero false alarms



Dedicated algorithms for solder balls detection









8x Angular Side Sensors (Only available for GTAz and GDAz models)

Simultaneously operating, multiplexed side view sensors with CameraLink interface — 45/45 arrangement — Triple use: Active automatic inspection, classification and repair — clear 9 angles defect review — high magnification 50x (10µm/pixel) — Full Color — Auto highlight — Large sensor pixels — 9 view images also in backup database



Hardware and Software Features — Continued

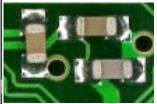
4 4 5 60

Double size FOV (Field of view)

Up to 2x faster inspection over previous generations of machines. Square FOV combined with circular lighting allows for program rotation without time consuming debugging.

Large pixel image capturing sensor

15µm² pixel size — less noise — smooth and detailed image— great dynamic range





High dynamics sensor

Conventional sensor

Height Adjustable Optical Head

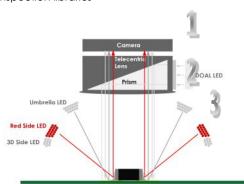
Z-Axis moving Top Camera, Light and Side View cameras — Adaption to any PCB Thickness — PCB Warp Compensation — Inspection of PCB's with very tall components — Reliable text and/or polarity inspection on tall components Inspection of "Sandwich" assemblies without need of jigs and multiple inspections

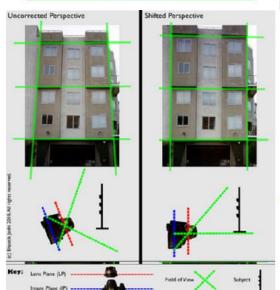
Omnidirectional multi angle, multi color LED lighting

Optimal light no matter component direction — 3D color profile of solder meniscus — Reliable defect decision by the software — Decide Good Solder, No Solder, Lack of Solder and Too much solder for SMT and THT solder joints

SMT Solder Inspection

Full solder profiling and histogram algorithm analysis. Simple prebuilt solder inspection libraries







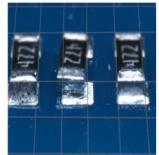


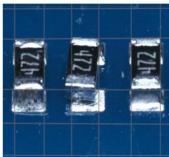


90° + 65° + 45° Meniscus Profiler Good solder

Shift & Tilt Side View lenses

Distortion free side images across whole FoV. Every point on the PCB within the FoV has same distance to the capturing sensor despite the angle of the optics





Without Shift&Tilt

Shift&Tilt



Inline BTL



Bottom & Top Simultaneous inspection JTAz + JDAz

In-Line Series Specifications	PowerSpector JTAz + JDAz 350BTL	PowerSpector JTAz + JDAz 550BTL	
Maximum PCB Size	350x250mm (13.8'x9.8")	550x550mm (21.6"x21.6")	
Characteristics			
Product type	Automatic Optical Inspector		
n-line/Off-line	In-Line		
Camera movement	X + Y Direction		
CB movement	Stationary during inspection		
arts inspection	Presence, Polarity, Offset, Correctness, Soldering, Height		
rinting/paste inspection	Offset, Smearing, Bridges, Uniformity		
mage Processing	Synthetic Imaging, Spectral Analysis, Greyscale limits		
mage Parameters	Brightness, Hue, Saturation via Filters		
Camera type	Digital color USB Vision interface 60 Fps		
Camera Field Of View/Resolution	36 x30mm/15µm		
ens	Telecentric lens with built in prism for DOAL Lighting		
ighting system	Omnidirectional T Triple LED rings: Side Red, Main, Line Sourced DOAL (Diffused Or Axis Lighting (Coaxial))		
Specifications			
imallest inspection component size	01005" (0.4x0.2mm)		
Positioning accuracy	Pixel related Feedback Loop		
Component clearance (top)	JTAz 30mm (1.2") JDAz 60 mm (2.4")		
ide Cameras	8x Digital color USB 3.0 Vision in 45/45 orientation		
Z-Axis movement range	30mm (1.2")		
Component clearance (bottom)	30mm (1.2") with JTAz bottom camera or 60mm (2.4") JDAz bottom camera		
Maximum PCB Size	350x250mm (13.8" x 9.8")	550x550mm (21.6" x 21.6")	
Novement speed	720mm/s		
nspection capacity typical	2750ppm		
Electrical requirements	100-240 VAC / 330W		
Conveyor		, , , , , , , , , , , , , , , , , , , ,	
Conveyor belt speed	10-500mm/s (0.4-19.7"/s)		
Conveyor configuration	Left>Right, Front rail fixed, Height 830-950mm		
CB Clamping	Top Justified, Ruler Blade, Top & Edge Clamping, Sensor Stopper		
Ainimum board size	50x50mm (2.0" x 2.0")		
Board thickness	0.6-4mm (24mils - 79mils)		
Interfacing			
Control PC type	Apple Mac Mini or iMac x2		
Control interface	SMEMA (coi	nveyer)	
Data interface	USB and Thunderbolt		
Programming Interface	CSV Centroid file (P	CSV Centroid file (Placement file)	
Repair/Monitor/SPC System/MES-interface	Mek Catch System (Windows 7/8/10) (option)		
Brd party Interfacing (MES) & Data Storage	Enterprise SQL DB/XML Files/Socket (Catch System Option)		
General			
Operating temperature	15-30 deg. C(60-90 deg. F)		
Operating humidity			
External size	W878 x D916 x H1313 (34.6" x 36.1" x 51.7")	W1078 x D1320 x H1317 (42.4" x 52" x 51.8")	
	1t 240kg (397lbs) 400kg (529lb		

Mek Europe reserves the right to change the design and specifications without notice. © Mek Europe BV, 2022

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Inline BTL



Bottom & Top Simultaneous inspection

JDz + JDz

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Specifications		· ·		
mallest inspection component size	01005" (0.4x0.2mm)			
ositioning accuracy	Pixel related Feedback Loop			
Component clearance (top)	JDz 40mm (1.5") extendable to 60mm			
iide Cameras	NA			
Z-Axis movement range	30mm (1.2")			
Component clearance (bottom)	30mm (1.2")			
Agximum PCB Size	350x250mm (13.8" x 9.8")	550x550mm (21.6" x 21.6")		
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Control PC type	Apple Mac Mini or iMac x2			
Control interface	SMEMA (con			
Data interface	USB and Thur			
Programming Interface	CSV Centroid file (Placement file)			
Repair/Monitor/SPC System/MES-interface	Mek Catch System (Windows 7/8/10) (option)			
ord party Interfacing (MES) & Data Storage	Enterprise SQL DB/XML Files/Socket (Catch System Option)			
General				
Operating temperature	15-30 deg. C(60-90 deg. F)			
Operating humidity	15-80 % RH			
Evlary at size	W878 x D916 x H1313	W1078 x D1320 x H1317		
External size	(34.6" x 36.1" x 51.7") (42.4" x 52" x 51.8") 240kg (397lbs) 400kg (529lbs)			

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